

Power MOSFET

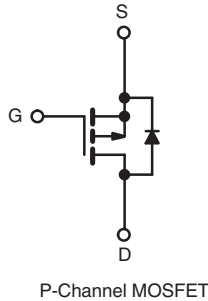
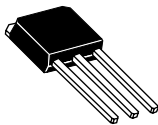
PRODUCT SUMMARY

V_{DS} (V)	- 250	
$R_{DS(on)}$ (Ω)	$V_{GS} = -10$ V	3.0
Q_g (Max.) (nC)	14	
Q_{gs} (nC)	3.1	
Q_{gd} (nC)	6.8	
Configuration	Single	

DPAK
(TO-252)



IPAK
(TO-251)



FEATURES

- P-Channel
- Surface Mount (IRFR9214/SiHFR9214)
- Straight Lead (IRFU9214/SiHFU9214)
- Advanced Process Technology
- Fast Switching
- Fully Avalanche Rated
- Lead (Pb)-free Available



Available
RoHS*
COMPLIANT

DESCRIPTION

Third generation Power MOSFETs from Vishay utilize advanced processing techniques to achieve low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The DPAK is designed for surface mounting using vapor phase, infrared, or wave soldering techniques. The straight lead version (IRFU/SiHFU series) is for through-hole mounting applications. Power dissipation levels up to 1.5 W are possible in typical surface mount applications.

ORDERING INFORMATION

Package	DPAK (TO-252)	DPAK (TO-252)	DPAK (TO-252)	IPAK (TO-251)
Lead (Pb)-free	IRFR9214PbF	IRFR9214TRLPbF ^a	IRFR9214TRPbF ^a	IRFU9214PbF
	SiHFR9214-E3	SiHFR9214TL-E3 ^a	SiHFR9214T-E3 ^a	SiHFU9214-E3
SnPb	IRFR9214	IRFR9214TRL ^a	IRFR9214TR ^a	IRFU9214
	SiHFR9214	SiHFR9214TL ^a	SiHFR9214T ^a	SiHFU9214

Note

a. See device orientation.

ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$, unless otherwise noted

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	- 250	V
Gate-Source Voltage			V_{GS}	± 20	
Continuous Drain Current	V_{GS} at - 10 V	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	- 2.7	A
		$T_C = 100\text{ }^{\circ}\text{C}$		- 1.7	
Pulsed Drain Current ^a			I_{DM}	- 11	
Linear Derating Factor				0.40	W/ $^{\circ}\text{C}$
Single Pulse Avalanche Energy ^b			E_{AS}	100	mJ
Repetitive Avalanche Current ^a			I_{AR}	- 2.7	A
Repetitive Avalanche Energy ^a			E_{AR}	5.0	mJ
Maximum Power Dissipation	$T_C = 25\text{ }^{\circ}\text{C}$		P_D	50	W
Peak Diode Recovery dV/dt^c			dV/dt	- 5.0	V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	- 55 to + 150	$^{\circ}\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s			260 ^d	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting $T_J = 25^\circ\text{C}$, $L = 27$ mH, $R_G = 25\ \Omega$, $I_{AS} = -2.7$ A (see fig. 12).
- $I_{SD} \leq -2.7$ A, $dI/dt \leq 600$ A/ μs , $V_{DD} \leq V_{DS}$, $T_J \leq 150^\circ\text{C}$.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	-	110	°C/W
Maximum Junction-to-Ambient (PCB Mount) ^a	R_{thJA}	-	-	50	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	-	2.5	

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA		- 250	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = - 1 mA		-	- 0.25	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA		- 2.0	-	- 4.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 250 V, V _{GS} = 0 V		-	-	- 100	μA
		V _{DS} = - 200 V, V _{GS} = 0 V, T _J = 125 °C		-	-	- 500	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 1.7 A ^b	-	-	3.0	Ω
Forward Transconductance	g _{fs}	V _{DS} = - 50 V, I _D = - 1.7 A		0.9	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1.0 MHz, see fig. 5		-	220	-	pF
Output Capacitance	C _{oss}			-	75	-	
Reverse Transfer Capacitance	C _{rss}			-	11	-	
Total Gate Charge	Q _g	V _{GS} = - 10 V	I _D = - 1.7 A, V _{DS} = - 200 V, see fig. 6 and 13 ^b	-	-	14	nC
Gate-Source Charge	Q _{gs}			-	-	3.1	
Gate-Drain Charge	Q _{gd}			-	-	6.8	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 125 V, I _D = - 1.7 A, R _G = 21 Ω, R _D = 70 Ω, see fig. 10 ^b		-	11	-	ns
Rise Time	t _r			-	14	-	
Turn-Off Delay Time	t _{d(off)}			-	20	-	
Fall Time	t _f			-	17	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal Source Inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	- 2.7	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	- 11	
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = - 2.7 A, V _{GS} = 0 V ^b		-	-	- 5.8	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = - 1.7 A, dI/dt = 100 A/μs ^b		-	150	220	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	870	1300	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

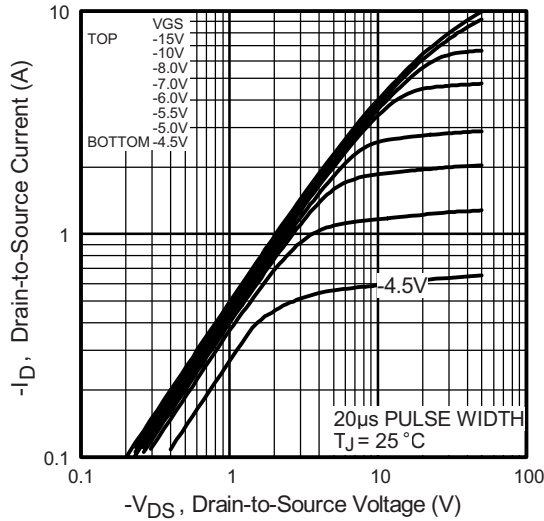


Fig. 1 - Typical Output Characteristics, $T_C = 25^\circ\text{C}$

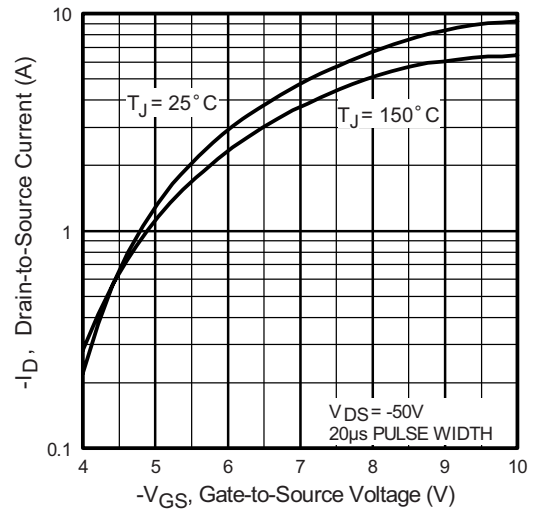


Fig. 3 - Typical Transfer Characteristics

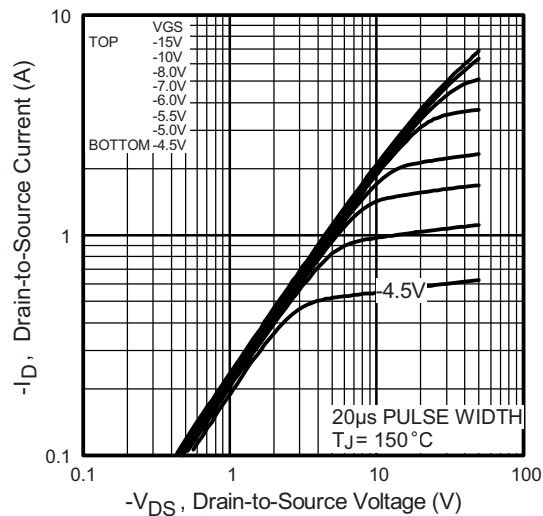


Fig. 2 - Typical Output Characteristics, $T_C = 150^\circ\text{C}$

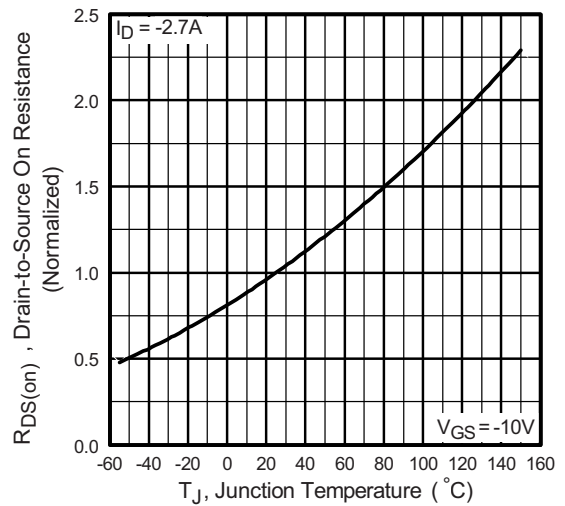


Fig. 4 - Normalized On-Resistance vs. Temperature

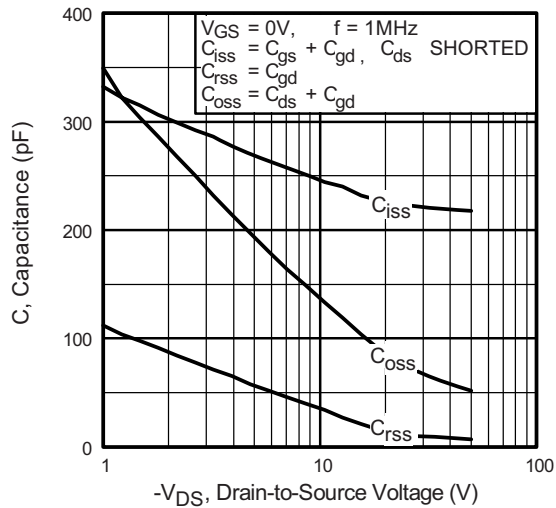


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

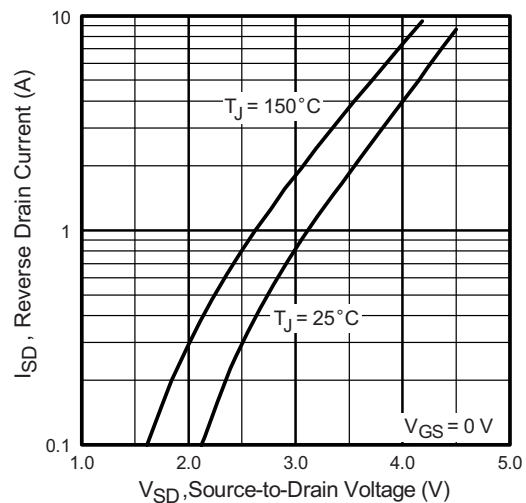


Fig. 7 - Typical Source-Drain Diode Forward Voltage

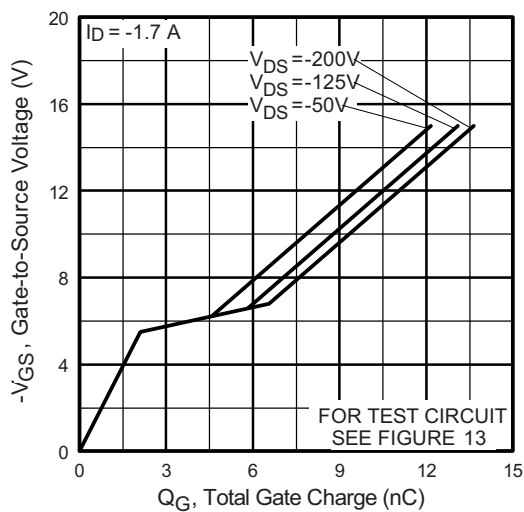


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

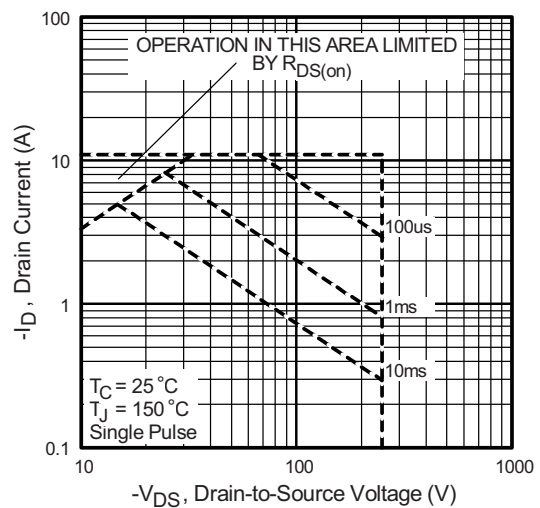


Fig. 8 - Maximum Safe Operating Area

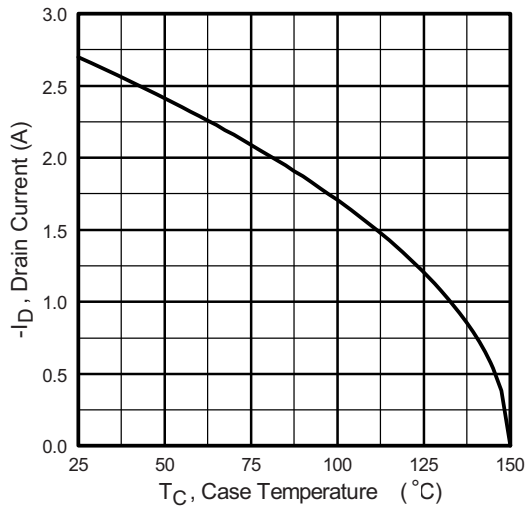


Fig. 9 - Maximum Drain Current vs. Case Temperature

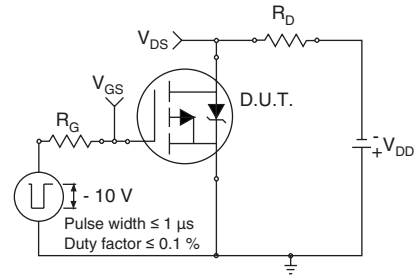


Fig. 10a - Switching Time Test Circuit

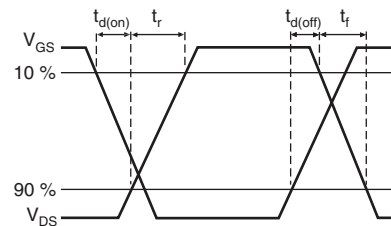


Fig. 10b - Switching Time Waveforms

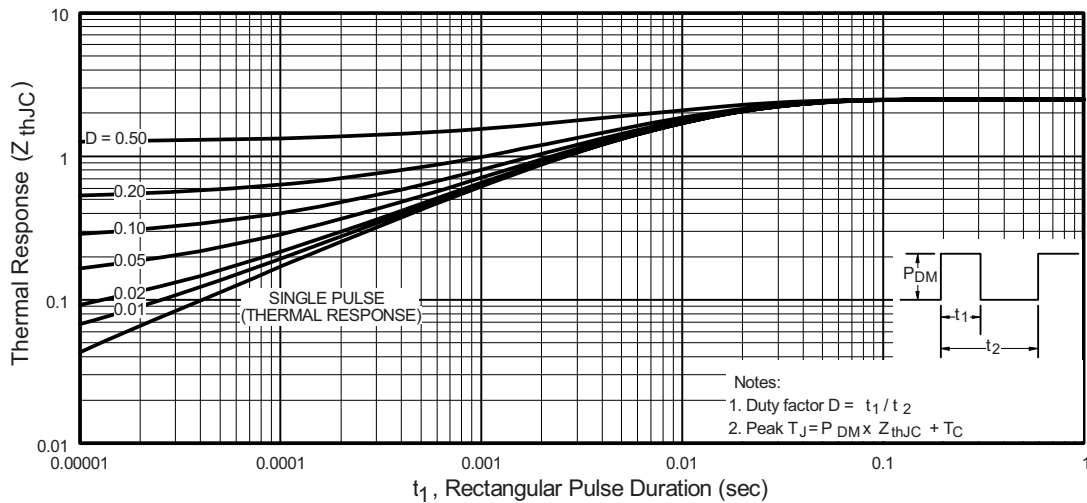


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

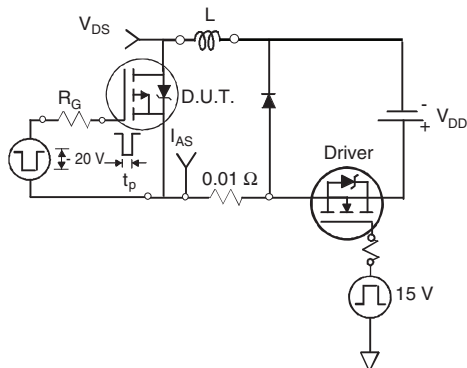


Fig. 12a - Unclamped Inductive Test Circuit

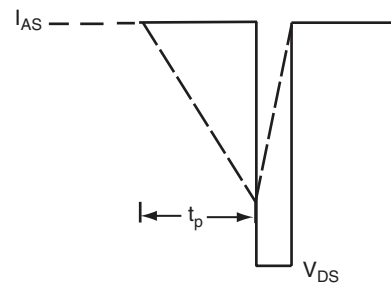


Fig. 12b - Unclamped Inductive Waveforms

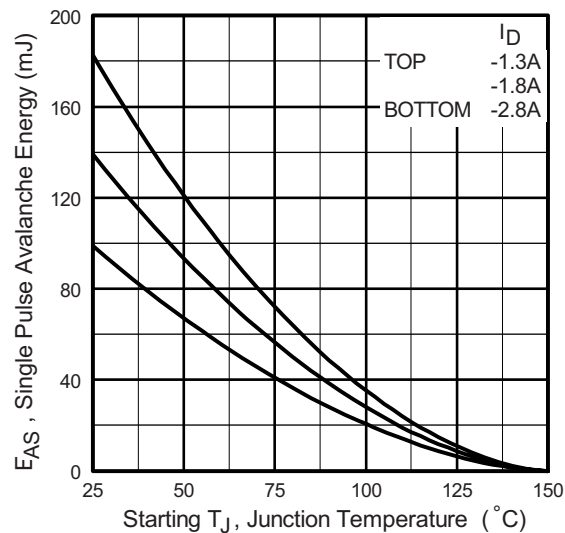


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

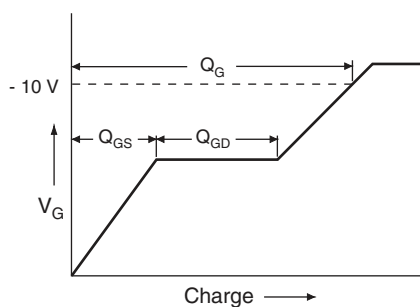


Fig. 13a - Basic Gate Charge Waveform

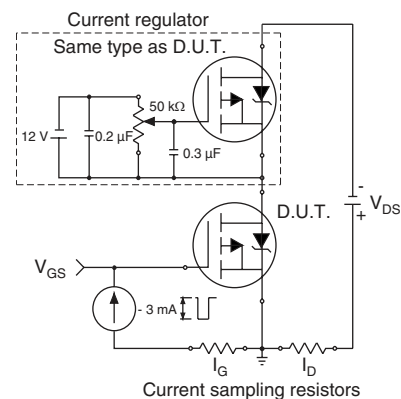
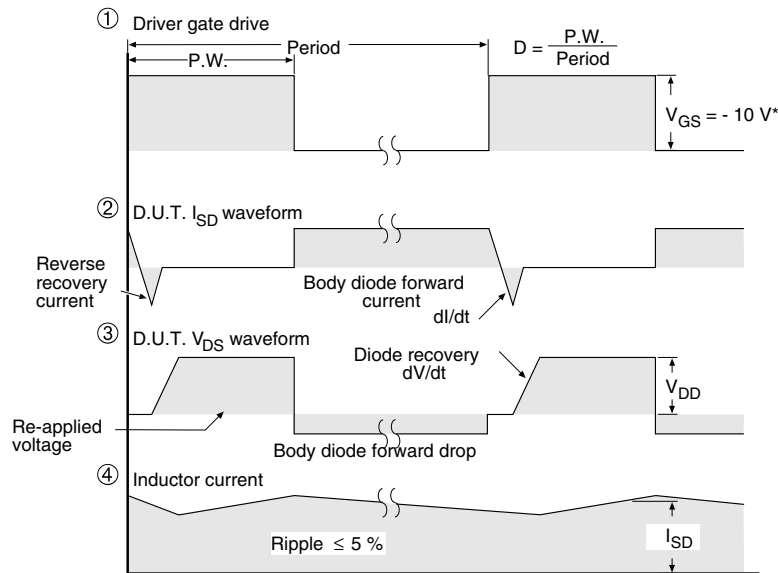
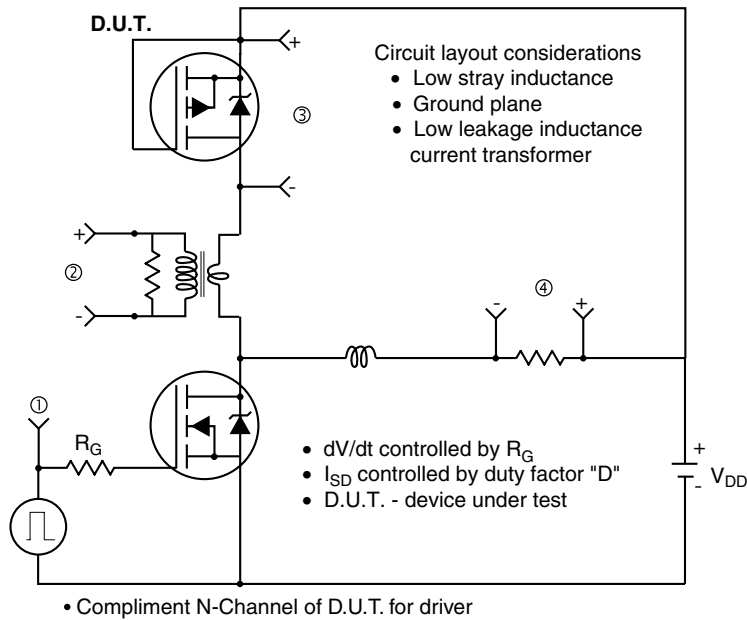


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



* $V_{GS} = -5\text{ V}$ for logic level and -3 V drive devices

Fig. 14 - For P-Channel



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